

Semico Fab Database Update Summary 2019

September 2019

MA102-19

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Excel Workbook

Below are the column headings included in the Excel workbook accompanying this Word document. There are over 1,000 rows in the workbook:

Status	MEMS
Company	Image Sensors
Previous Owner or Previous Company Name	Oth. Sensors
FabName	LED
Wafer Size (mm)	LED Drivers
Region	LCD Drivers
Country	Other
City	Bipolar
State/Region	Current Process Tech (nm)
Special Substrate	Capacity (wpm) 2010
University	Capacity (wpm) 2011
Development	Capacity (wpm) 2012
IDM	Capacity (wpm) 2013
Foundry	Capacity (wpm) 2014
Process Type	Capacity (wpm) 2015
Products	Capacity (wpm) 2016
Logic	Capacity (wpm) 2017
ASSPs	Capacity (wpm) 2018
ASICs	Capacity (wpm) 2019
Analog	Construction Start
Discretes	Initial Prod Yr
Passives	Vol Prod Yr
Opto	Most Recent Expansion/Construction Date
DRAM	Yr Closed or Closing
Mobile RAM	Employees
SRAM	Total Capex (millions)
NAND - 2D	Site Size
NAND - 3D	Total Fab Size (K sq. m)
XPoint	Cleanroom Size (K sq. m)
NOR	Updated Since Last Publish?
Other NV Memory	